

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	1.6mΩ@10V	160A

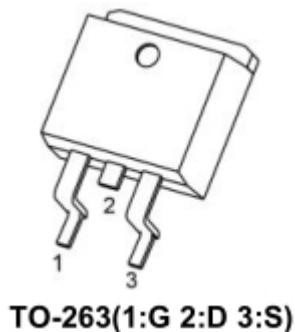
Feature

- Fast Switching
- Low Gate Charge and Rdson
- 100% Single Pulse avalanche energy Test

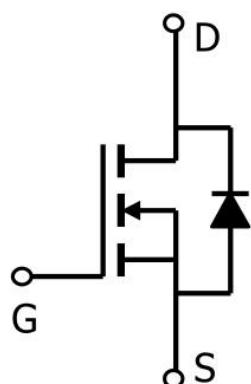
Application

- DC-DC Converter
- Ideal for high-frequency switching and synchronous rectification

Package



Circuit diagram



Marking



40N01BGH =Device Code
****** =Week Code

Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹ ($T_c=25^\circ\text{C}$)	I_D	160	A
Pulsed Drain Current ²	I_{DM}	640	A
Single Pulse Avalanche Energy ³	E_{AS}	529	mJ
Total Power Dissipation ⁴ ($T_c=25^\circ\text{C}$)	P_D	185	W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	0.67	$^\circ\text{C}/\text{W}$
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ\text{C}$

Electrical characteristics

($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	$\text{BV}_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 32\text{V}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			± 100	μA
Gate-source threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	4	V
Static Drain-Source On-Resistance ²	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 30\text{A}$		1.6	2.5	$\text{m}\Omega$
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		3485		pF
Output Capacitance	C_{oss}			1208		
Reverse Transfer Capacitance	C_{rss}			59		
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = 20\text{V}, V_{GS} = 10\text{V}, I_D = 65\text{A}$		57		pF
Gate-Source Charge	Q_{gs}			9.5		
Gate-Drain Charge	Q_{gd}			11		
Turn-On Delay Time	$T_{d(on)}$	$V_{DD} = 20\text{V}, V_{GS} = 10\text{V}, R_G = 1.6\Omega, I_D = 65\text{A}$		10		nS
Rise Time	T_r			3		
Turn-Off Delay Time	$T_{d(off)}$			35		
Fall Time	T_f			4		
Diode Characteristics						
Diode Forward Voltage ²	V_{SD}	$V_{GS} = 0\text{V}, I_S = 20\text{A}, T_J = 25^\circ\text{C}$			1.2	V

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is $V_{DD} = 15\text{V}, V_{GS} = 10\text{V}, L = 0.5\text{mH}, R_G = 25\Omega$

Typical Characteristics

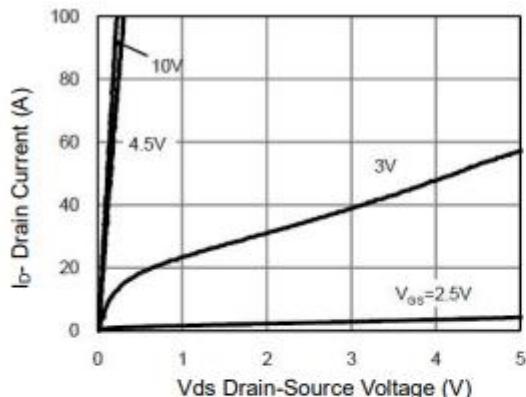


Figure 1 Output Characteristics

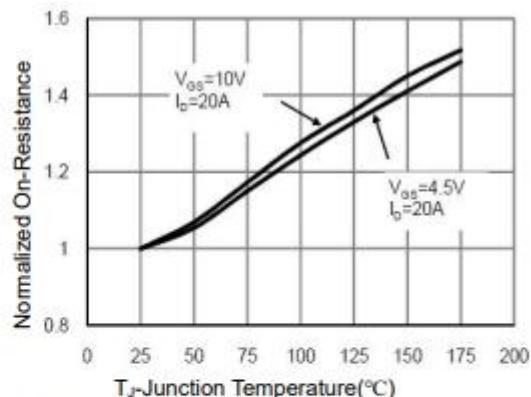


Figure 4 Rdson-Junction Temperature

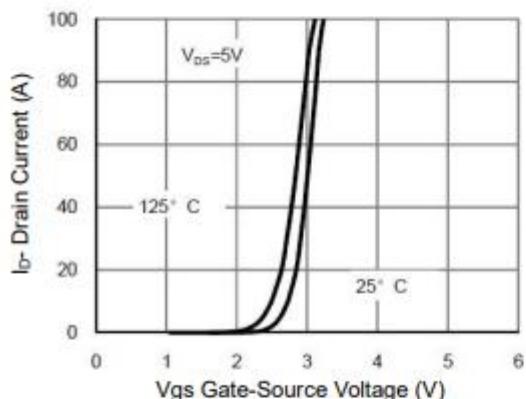


Figure 2 Transfer Characteristics

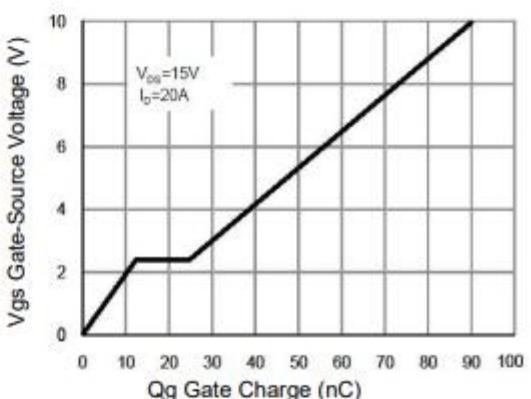


Figure 5 Gate Charge

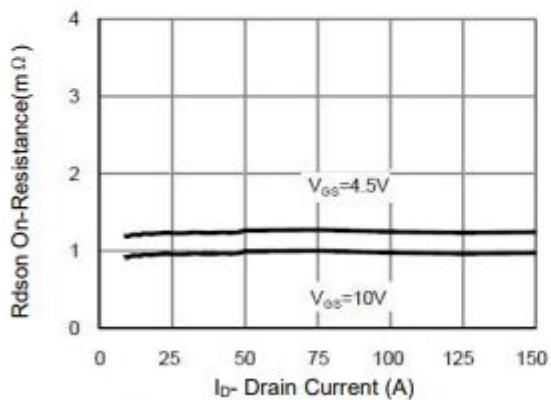


Figure 3 Rdson- Drain Current

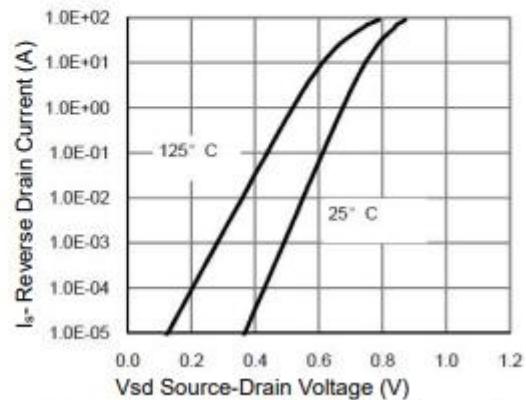
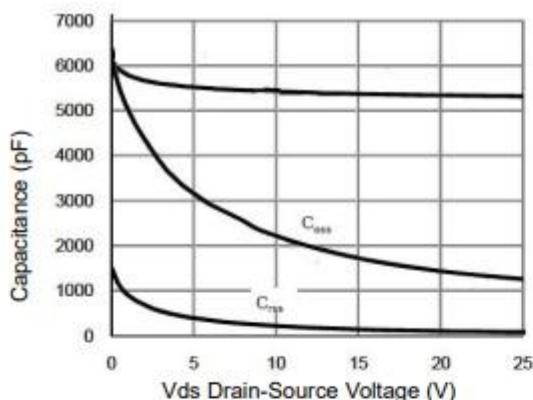
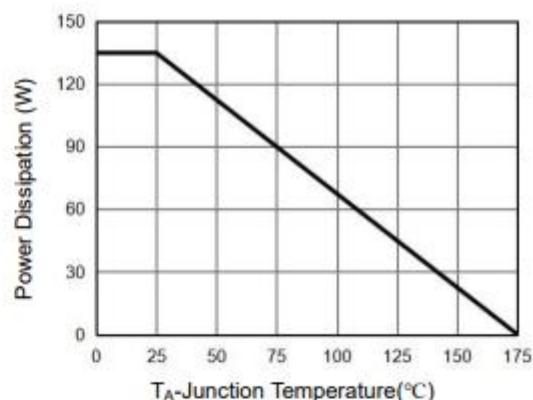
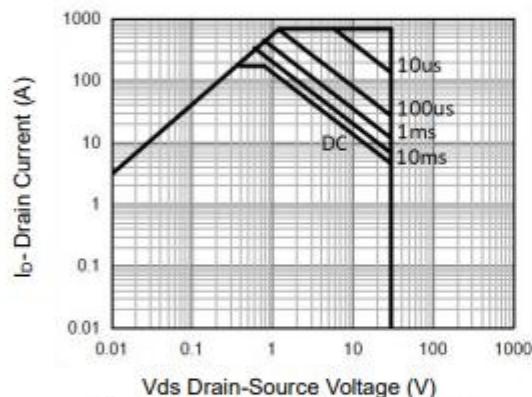
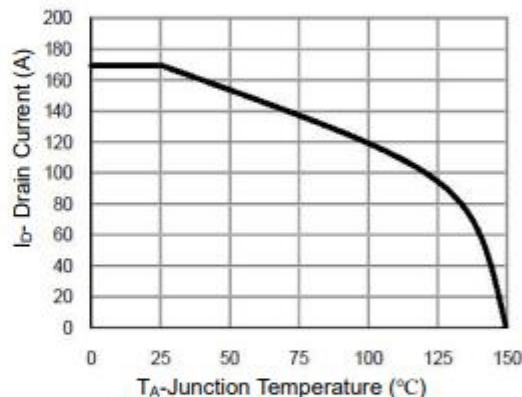
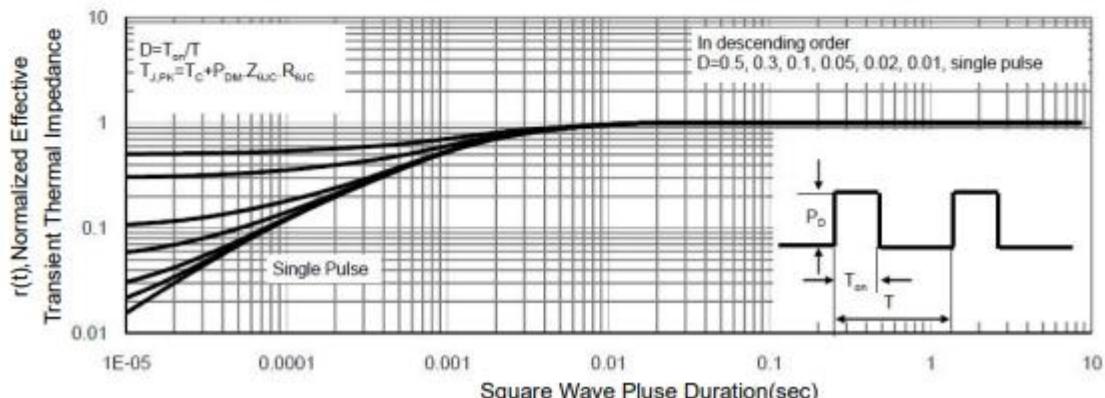
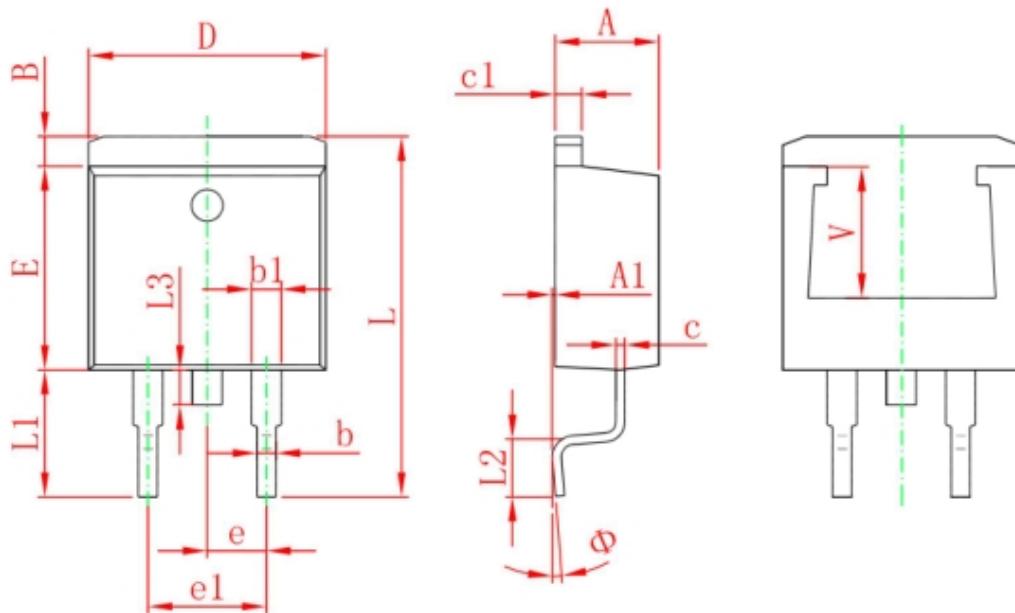


Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area (Note3)

Figure 10 Current De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance

TO-263 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.120	1.420	0.044	0.056
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
L	14.940	15.500	0.588	0.610
L1	4.950	5.450	0.195	0.215
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
Φ	0°	8°	0°	8°
V	5.600 REF.		0.220 REF.	